



SOT376-1

plastic thin quad flat package; 44 leads; body 10 x 10 x 1.0 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	TQFP44
Package type industry code	TQFP44
Package style descriptive code	TQFP (thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	137E08
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	14-3-2002

Table 1. Package summary

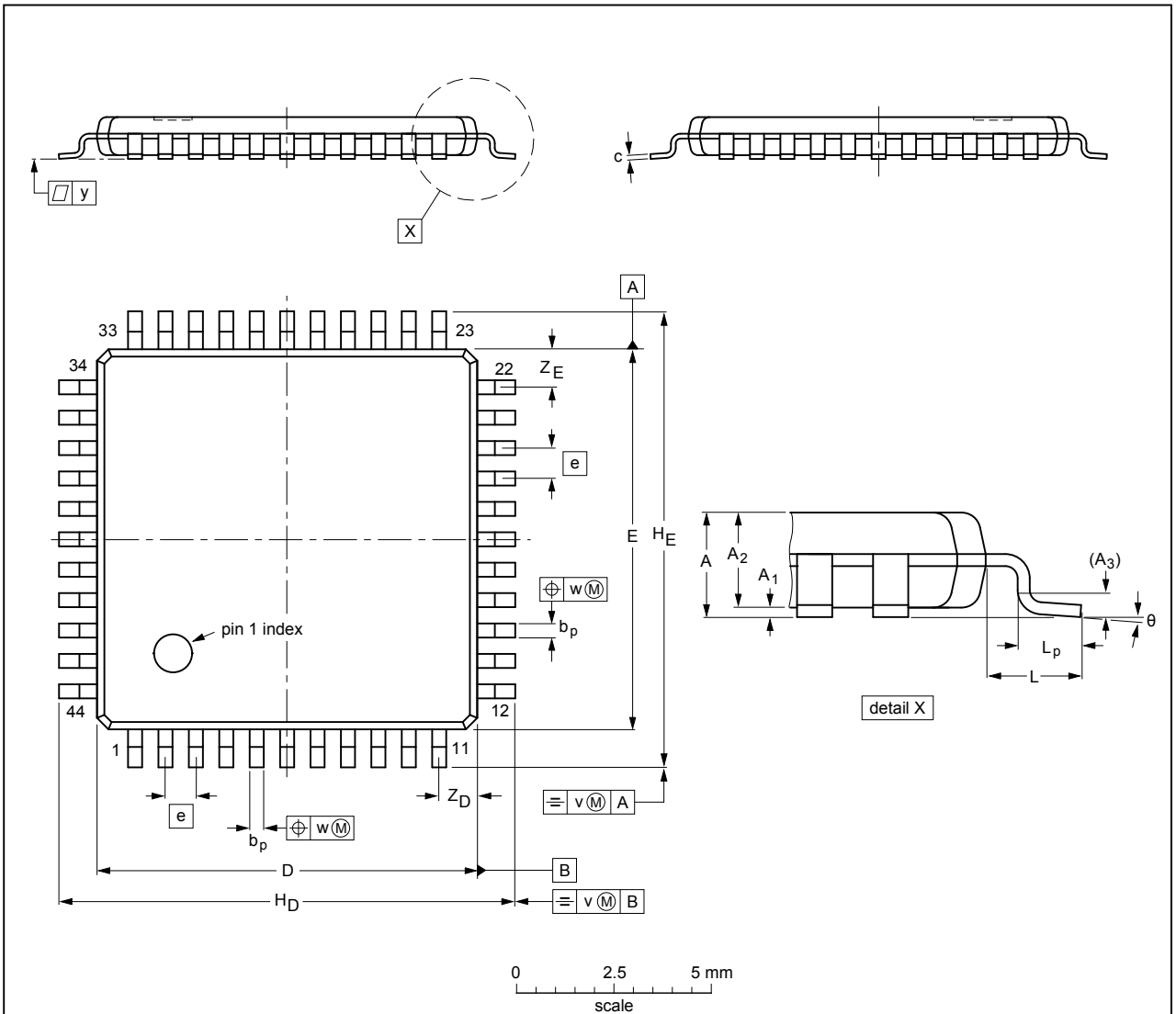
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.95	-	1	1.05	mm
n ₂	actual quantity of termination	-	-	44	-	



2. Package outline

TQFP44: plastic thin quad flat package; 44 leads; body 10 x 10 x 1.0 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.2	0.15 0.05	1.05 0.95	0.25	0.45 0.30	0.18 0.12	10.1 9.9	10.1 9.9	0.8	12.15 11.85	12.15 11.85	1	0.75 0.45	0.2	0.2	0.1	1.2 0.8	1.2 0.8	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT376-1	137E08	MS-026			00-04-19 02-03-14

Fig. 1. Package outline TQFP44 (SOT376-1)

3. Soldering

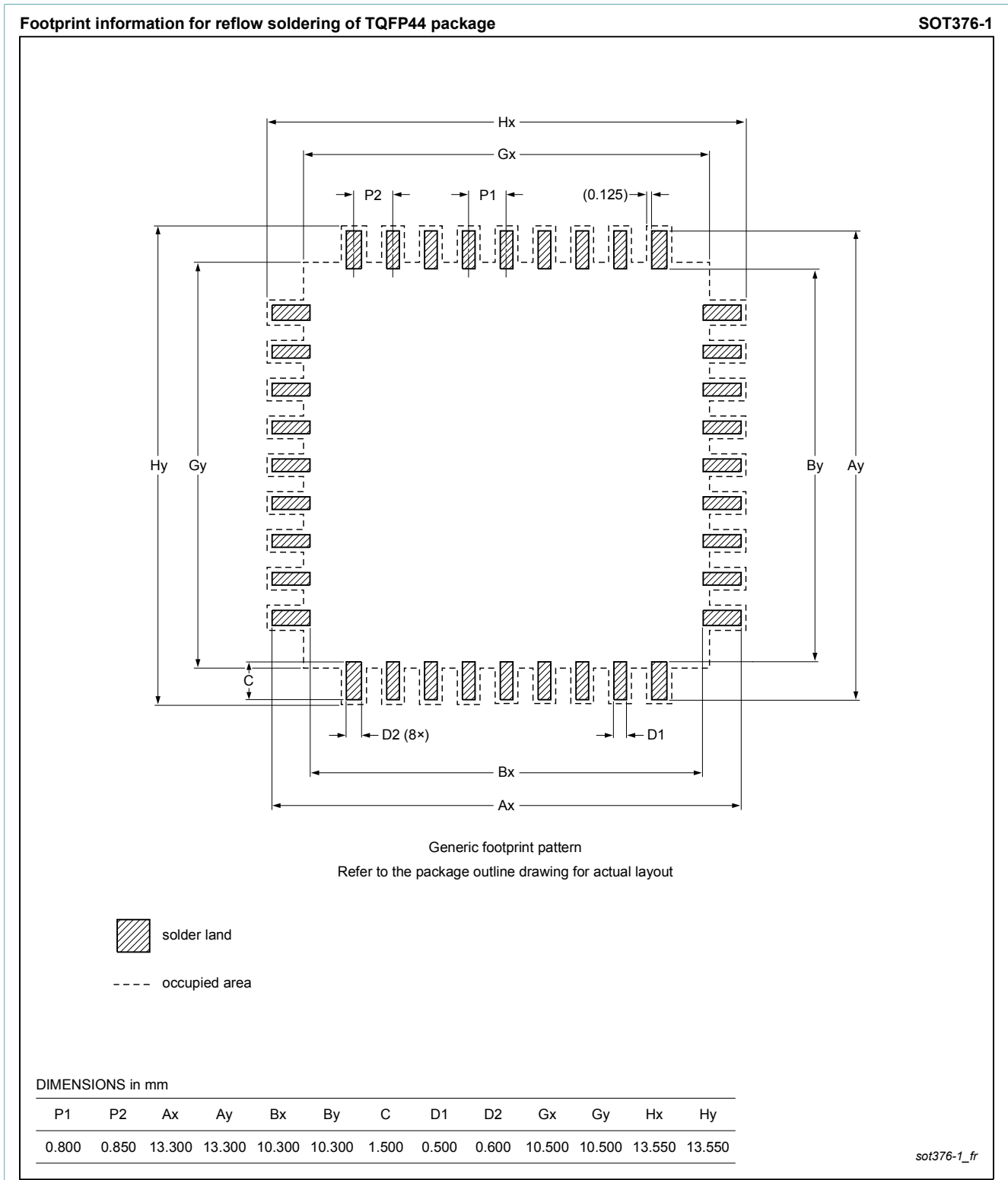
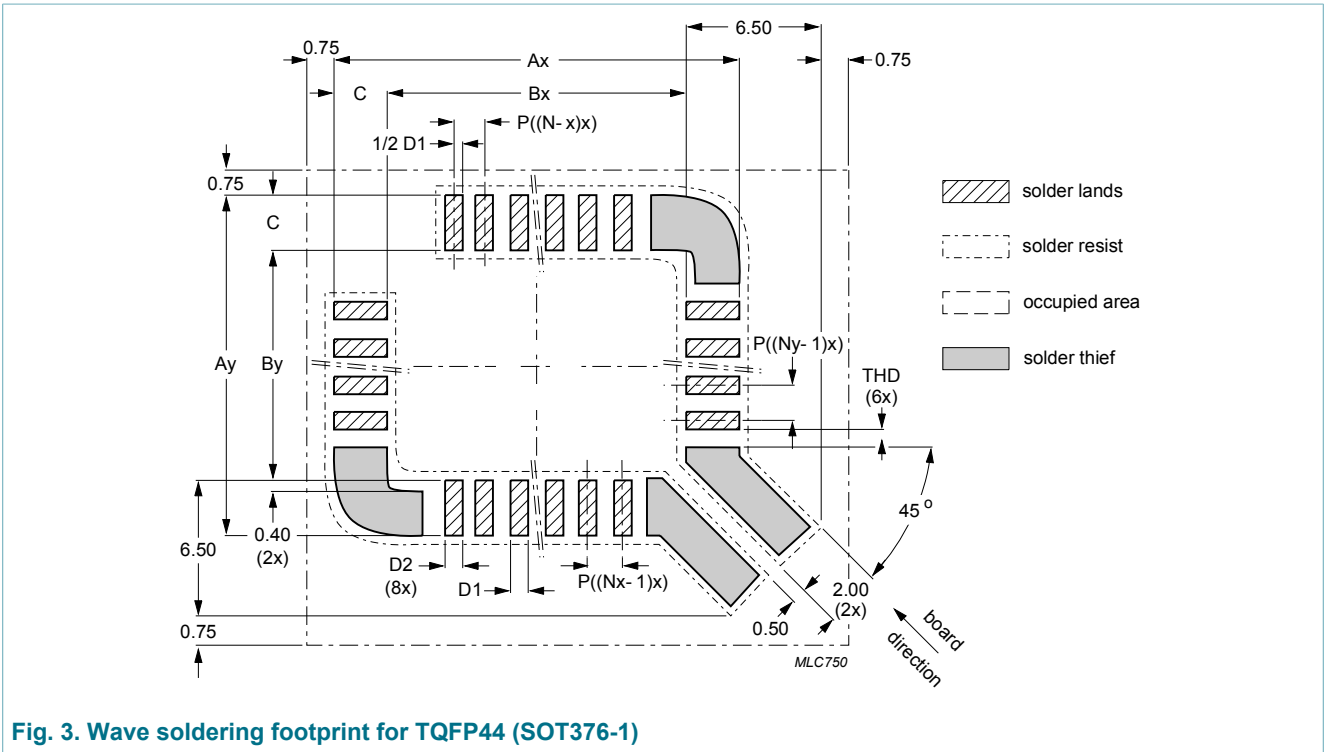


Fig. 2. Reflow soldering footprint for TQFP44 (SOT376-1)

plastic thin quad flat package; 44 leads; body 10 x 10 x 1.0 mm



4. Legal information

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